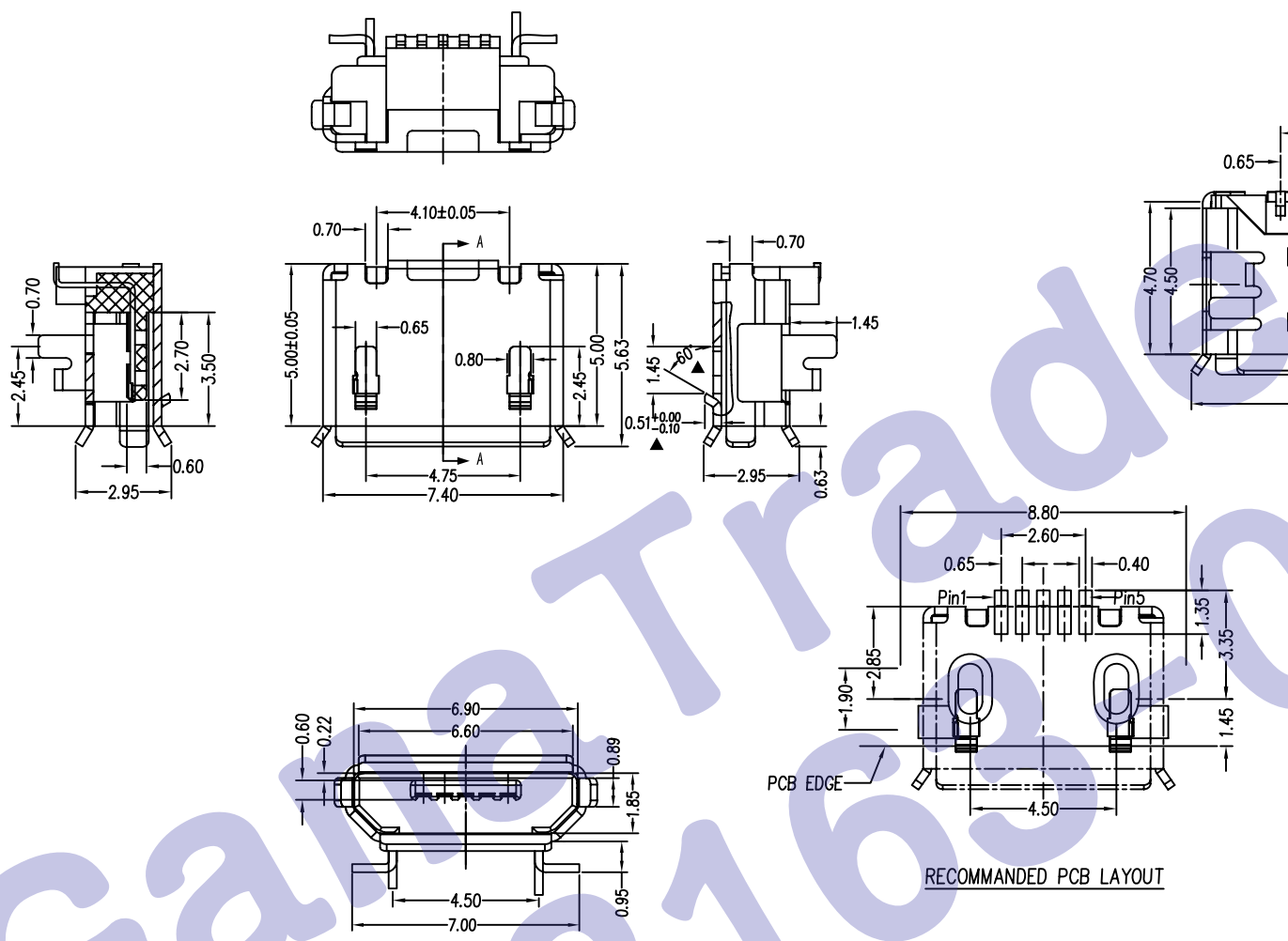


5 4 3 2 1

D

B

A



- Notes:
1. Materials:
    - 1.1 Housing: High temperature thermoplastic with g.f,UL94 v-0.
    - 1.2 Contact: copper alloy,t=0.20mm.
    - 1.3 Shell: copper alloy,t=0.25mm.
  2. Specifications:
    - 2.1. Current rating: 1 A Max.
    - 2.2. Dielectric withstanding:voltage: 100 V(ac) for 1 min.
    - 2.3. Contact resistance: 50 mW Max.
    - 2.4. Insulation resistance: 100 MW Min.
    - 2.5. Total mating force: 3.57 Kgf Max.
    - 2.6. Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
    - 2.7. Temperature range: -30°C~+80°C

|                  |    |                  |     |
|------------------|----|------------------|-----|
| 设计<br>DRAW BY    | 杨帆 | 审核<br>DISCUSS BY |     |
| 校对<br>DISCUSS BY |    | 比例<br>SCALE      | 2:1 |

HDC有限公司

|                  |                            |                |     |              |             |
|------------------|----------------------------|----------------|-----|--------------|-------------|
| 图名<br>DRAWING NO | MICRO USB B TYPE 垫高DIP+SMT | 图号<br>SHEET NO | 112 | 日期<br>DATE   | 2012.02.15  |
| 料号<br>VERSION    |                            | 数量<br>QUAN     |     | 备注<br>REMARK | 张号<br>SHEET |
|                  |                            |                |     | 版次<br>REMARK | 1/1         |

6 5 4 3 2 1